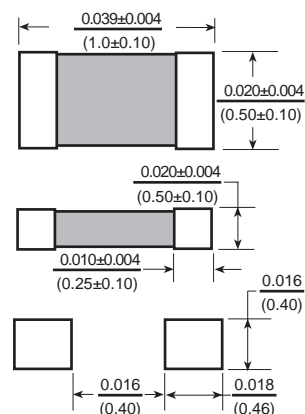


Dimensions:  $\frac{\text{Inches}}{\text{(mm)}}$



Allied Part Number	Impedance ( $\Omega$ ) @ 100 MHz +/- 25%	DC Resistance ( $\Omega$ ) Max.	*Rated Current (mA)
MLB03-100-RC	10	0.05	500
MLB03-400-RC	40	0.20	500
MLB03-600-RC	60	0.20	500
MLB03-700-RC	70	0.20	500
MLB03-101-RC	100	0.25	500
MLB03-121-RC	120	0.25	500
MLB03-221-RC	220	0.40	400
MLB03-301-RC	300	0.50	300
MLB03-471-RC	470	0.50	300
MLB03-601-RC	600	0.60	300
MLB03-102-RC	1000	0.95	200
MLB03-182-RC	1800	1.40	100
MLB03-222-RC	2200	1.40	100

\*Temperature rise  $\Delta T=30^{\circ}\text{C}$  at rated current.  
All specifications subject to change without notice.

### Features

- Surface mount EMI suppression components
- Nickel barrier termination for excellent resistance to solder heat
- Multi layer technology
- Flow and reflow soldering

### Electrical

**Impedance Range:** 10 $\Omega$  to 2200 $\Omega$

**Tolerance:** 25% over entire range

**Operating Range:** -55 $^{\circ}\text{C}$  ~ +125 $^{\circ}\text{C}$

**Storage Temp:** Under 25 $^{\circ}\text{C}$  at 40~60% Humidity

**Rated Current:** Based on temp rise not to exceed 30 $^{\circ}\text{C}$

### Resistance to Solder Heat

Pre-Heat 150 $^{\circ}\text{C}$ , 1 minute

Solder Composition: Sn/Ag3.0/Cu0.5

Solder Temp: 260 $\pm$ 5 $^{\circ}\text{C}$  for 10sec  $\pm$ 1 sec.

Minimum of 75% of Electrode covered with new solder.

Impedance within 30% of initial value.

### Test Equipment

(Z): HP4291A RF Impedance/Material Analyzer

(RDC): Chen Hwa 502BC

### Physical

**Packaging:** 10000 per 7 inch reel.

**Marking:** None